

/ Descriptions

1000V 1.0A SMA
Surface Mount Superfast Recovery Rectifier,Reverse Voltage:1000V,Forward Current:1.0A, SMA package.

/ Features

RoHS 2011/65/EU
Glass Passivated Chip Junction Superfast reverse recovery time Lead free in comply with EU R0HS 2011/65/EU directives For surface mounted applications,HF product.

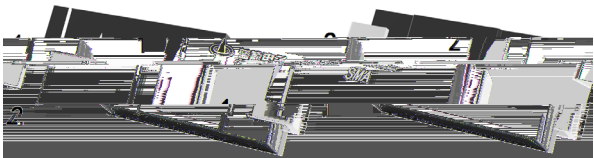
/ Applications

General purpose.

/ Equivalent Circuit

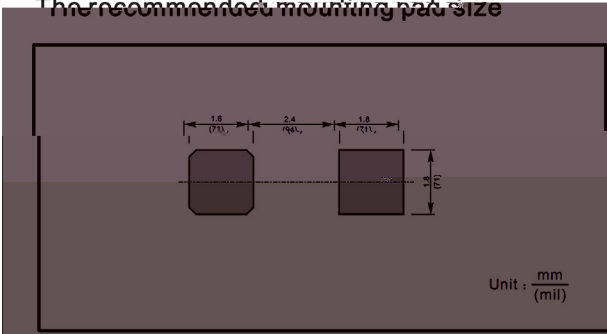


/ Pinning



PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



/ Marking

See Marking Instructions.

Parameter	Symbol	Rating	Unit
		ES1M	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	1000	V
Maximum RMS voltage	V_{RMS}	700	V
Maximum DC Blocking Voltage	V_{DC}	1000	V
Maximum Average Forward Rectified Current	$I_{F\ AV}$	1.0	A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	30	A
Typical Junction Capacitance at $V_R = 4V, f = 1MHz$	C_j	20	pF
Typical Thermal Resistance ¹	$R_{\theta JA}$	75	/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55~+150	

Note:

1 P.C.B. mounted with 1.0 X 1.0" (2.54 X 2.54 cm) copper pad areas.

ES1M

Rev.A Aug.-2023

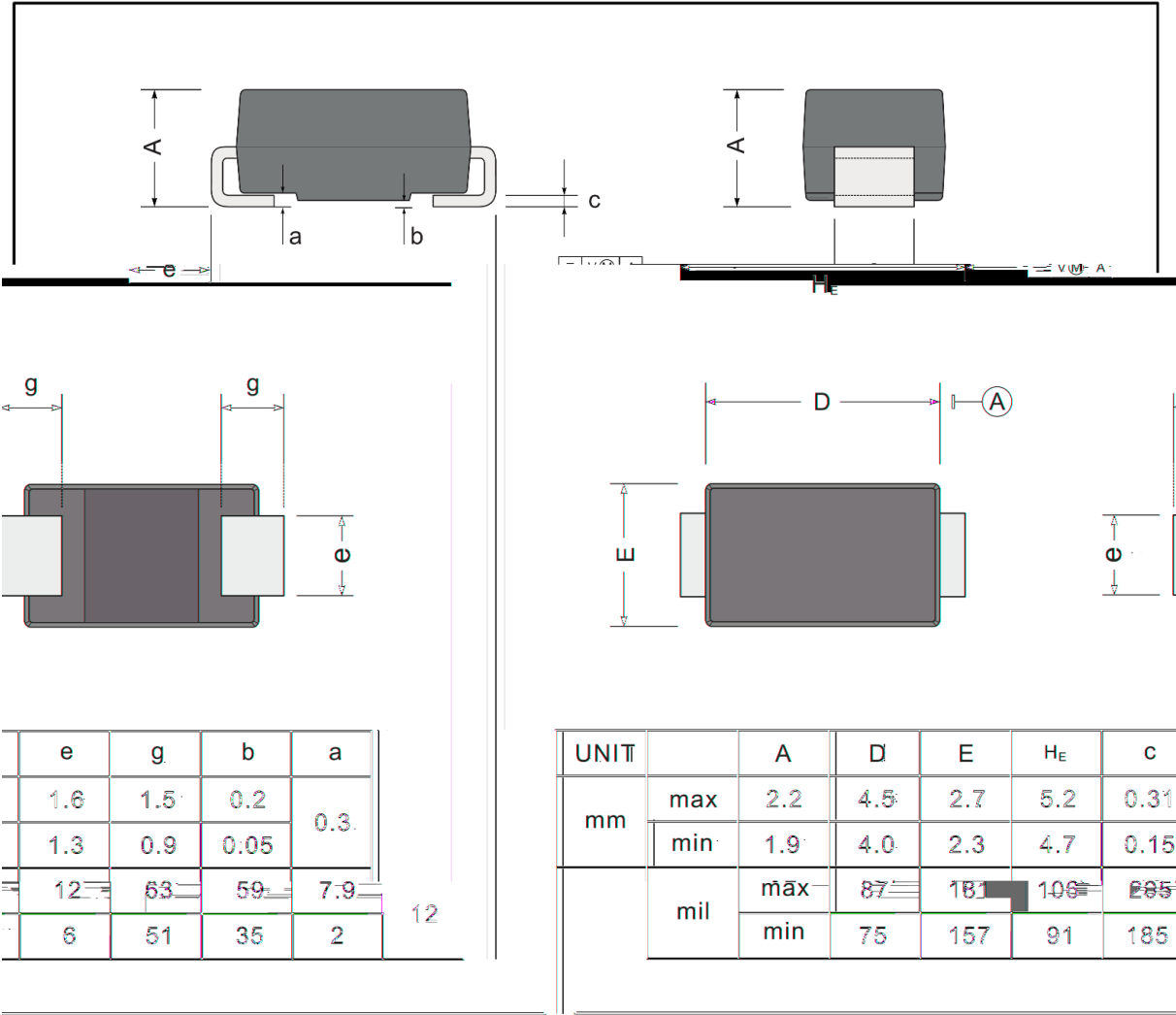


蓝箭电子
BLUE ROCKET ELECTRONICS

DATA SHEET

/ Package Dimensions

SMA



/ Marking Instructions



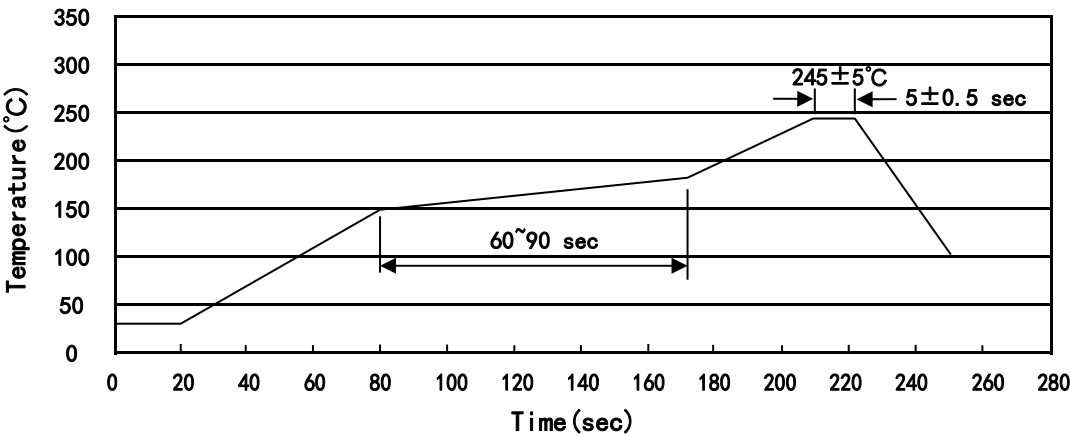
ES1M

Note:

ES1M Product Type Code

***** Lot No. Code, code change with Lot No

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

150 180

60 90sec;

1.Preheating:150~180 , Time:60~90sec.
- 2

245±5

5±0.5sec;

2.Peak Temp.:245±5 , Duration:5±0.5sec.
- 3

2 10 /sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
SMA	5,000	2	10,000	7	70,000	13 ×12	336×336×40	380×335×366

/ Notices